

IN THE DRAWINGS:

The objection to the drawings has been complied with by the claiming of the term: "host card" indirectly rather than directly, in the amended claims 1 through 17, and 27 through 30.

IN THE CLAIMS:

Please amend claims 1 - 4, 6, 8, 9, 11 - 13, 15, 16, 23, 24, 27, and 29 as follows:

sub. C1 1. (Amended) A package article for removably accepting a fiber optic cable, said package article being adaptable for operatively connecting to a host card, comprising:

a laminate for supporting optoelectronic components;

B1 an amplifier die operatively connected to and supported by said laminate for amplifying electrical signals;

a flexible circuit electrically connected to and supported by said laminate for receiving said amplified electrical signals from said amplifier die; and

perpendicular to the plane of
the substrate

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an optoelectronic die electrically connected to said flexible circuit for receiving said amplified electrical signals generated by said amplifier die and for generating optical signals responsive thereto.

2. (Amended) The package article for removably accepting a fiber optic cable in accordance with claim 1, said package article further comprising:

a heat sink carrier operatively connected to said flexible circuit, and attached to said optoelectronic die for removing heat therefrom.

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3. (Amended) The package article for removably accepting a fiber optic cable in accordance with claim 1, said package article further comprising:

an optical subassembly having means for optically aligning with said optoelectronic die for receiving and processing said optical signals therefrom, said optical subassembly comprising an optical coupler and a removable optical connector having an optical cable.

4. (Amended) An optoelectronic subassembly for accepting optical signals from a fiber optic cable, said optoelectronic subassembly having means for operatively connecting to a host card, said optoelectronic subassembly comprising:

an optoelectronic die for receiving electrical signals and for generating optical signals responsive thereto;

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a flexible circuit electrically connected to said optoelectronic die;

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an optical coupler optically connected to said optoelectronic die for receiving optical signals therefrom; and

a heat sink carrier operatively connected to said flexible circuit, and attached to said optoelectronic die for removing heat therefrom.

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6. (Amended) The optoelectronic subassembly for accepting optical signals from a fiber optic cable in accordance with claim 5, wherein said optical connector further comprises an optic cable.

8. (Amended) The package article in accordance with claim 7, further comprising:

a laminate for supporting optoelectronic components;

an amplifier die operatively connected to and supported by said laminate for amplifying electrical signals;

B3 an optical subassembly in optical communication with said optoelectronic die for receiving and processing said optical signals therefrom, said optical subassembly comprising an optical coupler and a removable optical connector having an optic cable; and

a retainer operatively connected to said optical coupler and removably connected to said optical connector for aligning said optical coupler and optical connector.

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9. (Amended) A package article for removably accepting a horizontally oriented fiber optic cable, and being adaptable to operatively connecting to a host card, comprising: a flexible circuit disposed between at least one translating die operatively connected to a laminate, and an optoelectronic die; means defining two heat sink carriers; said horizontally oriented fiber optic cable connected to said at least one translating die such that said fiber optic cable exits from said laminate in a direction substantially parallel to a horizontal plane defining an orientation of said laminate; an overmold frame that is supported by said laminate, said overmold frame having a cavity for receiving said flexible circuit, said optoelectronic die and said at least one heat sink carrier; at least one of said heat sink carriers being operatively connected to said optoelectronic die; said cavity of said overmold frame enclosing and securing at least one heat sink carrier, said optoelectronic die and said flexible circuit.

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11. (Amended) The package article in accordance with claim 9, further comprising at least one faraday barrier shield supported by said overmold frame housing, said at least one faraday barrier shield providing RF isolation of said optoelectronic die.

12. (Amended) The package article in accordance with claim 9, further comprising a fiber optic coupling disposed between said optoelectronic die and said fiber optic cable.

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Cmt . 13. (Amended) The package article in accordance with claim 12, further comprising a retainer, and wherein said fiber optic coupling disposed between said optoelectronic die and said fiber optic cable is snap connected to said retainer, said retainer being attached to said heat sink carrier.

15. (Amended) The package article in accordance with claim 12, wherein said fiber optic coupling comprises an optical coupler connected to said optoelectronic die at one end, said optical coupler being attached to an optical connector at an opposite end, said optical connector being connected to said fiber optic cable.

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16. (Amended) A package article for coupling a horizontally oriented set of fiber optic cables to vertically oriented translating dies, comprising: at least one fiber optic cable, said at least one fiber optic cable being oriented substantially parallel to a plane defining a substantially horizontally oriented laminate, a flexible circuit operatively disposed between said laminate and said at least one fiber optic cable, such that said at least one fiber optic cable exits from said laminate in a direction substantially parallel to a horizontal plane defining an

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Cont. orientation of said laminate, an overmold frame that is supported by said laminate, a heat sink carrier and at least one optoelectronic die supported by said overmold frame, said overmold frame having a cavity for receiving said flexible circuit, said at least one optoelectronic die and said heat sink carrier.

23. (Amended) A transmitting optoelectric subassembly for accepting a parallel fiber optic connector that is secured to one end of a parallel fiber optic cable, comprising:

B6 an optoelectronic subassembly comprising a transmitting optoelectronic device secured to a carrier, an electrical signal transfer device, and an optical coupler signal transfer device both being secured to a retainer and to said carrier; and

an electronic subassembly comprising an overmold frame secured to a laminate and to said retainer.

24. (Amended) The package in accordance with claim 23, wherein said electrical signal transfer device electronically couples an electronic signal from said electronic subassembly to said transmitting optoelectronic device, said transmitting optoelectronic device converts said electronic signal to an optical signal, said optical signal transfer device optically couples said optical signal to said parallel fiber optic

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cont. connector, and said retainer removably retains said parallel fiber optic connector.

See C27 27. (Amended) A method for coupling at least one fiber optic cable to at least one translating die, comprising:

applying an electrical signal from an amplifier die to a flexible circuit disposed on a laminate to which a host card can be electrically connected;

B7 converting said electrical signal to an optical signal; and

applying said optical signal to an optical coupler for transmitting said optical signal to an optical connector attached to said at least one fiber optic cable.

B8 29. (Amended) The method for coupling at least one fiber optic cable to at least one translating die in accordance with claim 28, the steps further comprising:

providing a plurality of heat sink pathways for performing said heat removing step.
